SS52F THRU SS520F

Surface Mount Schottky Barrier Rectifier

Reverse Voltage - 20 to 200V
Forward Current - 5.0A

FEATURES

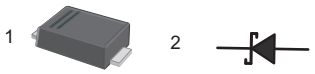
- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

MECHANICAL DATA

- Case: SMAF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 27mg / 0.00095oz

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Top View
Marking Code: SS52~SS520
Simplified outline SMAF and symbol

Absolute Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

Parameter	Symbols	SS52F	SS54F	SS56F	SS58F	SS510F	SS512F	SS515F	SS520F	Units
	Marking	SS52	SS54	SS56	SS58	SS510	SS512	SS515	SS520	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	20	40	60	80	100	120	150	200	V
Maximum RMS voltage	V_{RMS}	14	28	42	56	70	84	105	140	V
Maximum DC Blocking Voltage	V_{DC}	20	40	60	80	100	120	150	200	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	5.0								A
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	120								A
Max Instantaneous Forward Voltage at 5 A	V_F	0.55		0.70		0.85				V
Maximum DC Reverse Current T_a = 25°C at Rated DC Reverse Voltage T_a =100°C	I_R	1.0 50								mA
Typical Junction Capacitance (1)	C_j	500		300						pF
Typical Thermal Resistance (2)	$R_{\theta JA}$	60								°C/W
Operating Junction Temperature Range	T_j	-55 ~ +150								°C
Storage Temperature Range	T_{stg}	-55 ~ +150								°C

(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.
(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

WPMtek

Fig.1 Forward Current Derating Curve

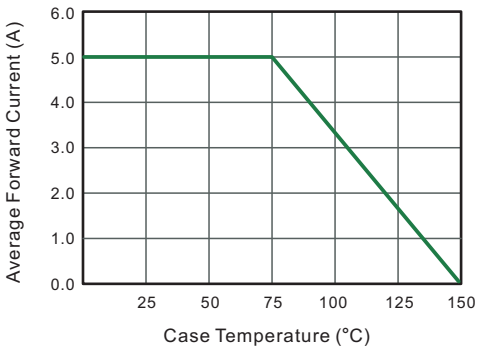


Fig.2 Typical Reverse Characteristics

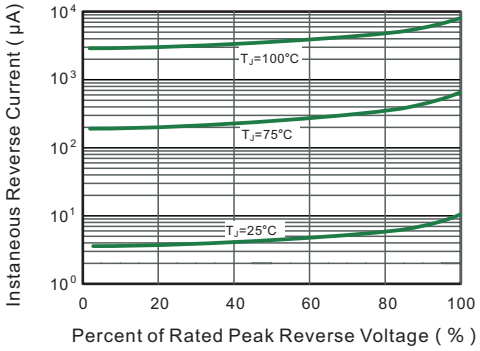


Fig.3 Typical Forward Characteristic

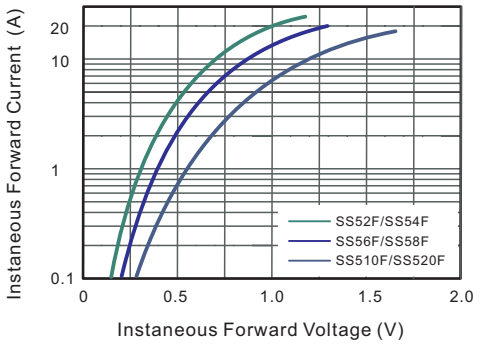


Fig.4 Typical Junction Capacitance

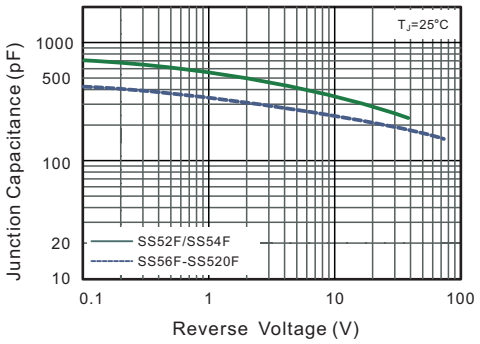


Fig.5 Maximum Non-Repetitive Peak Forward Surage Current

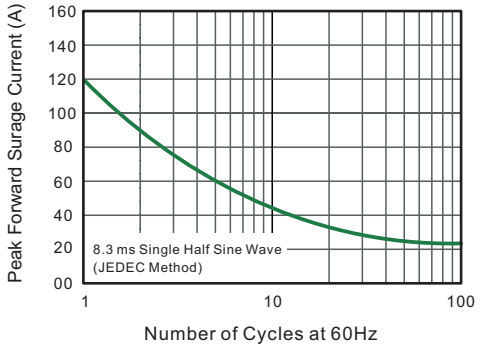
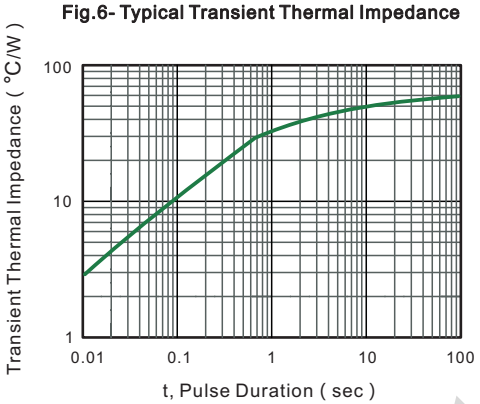


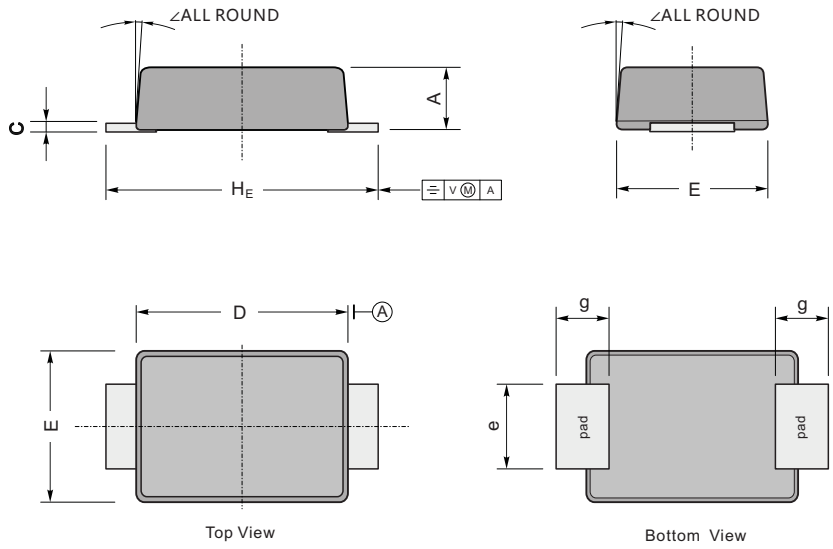
Fig.6- Typical Transient Thermal Impedance



WPMtek

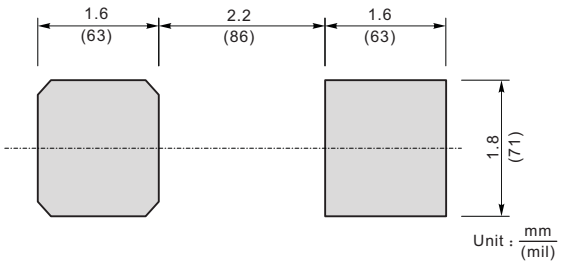
PACKAGE OUTLINE

Plastic surface mounted package; 2 leads **SMAF**



UNIT		A	C	D	E	e	g	H_E	∠
mm	max	1.2	0.20	3.7	2.7	1.6	1.2	4.9	7°
	min	0.9	0.12	3.3	2.4	1.3	0.8	4.4	
mil	max	47	7.9	146	106	63	47	193	
	min	35	4.7	130	94	51	31	173	

The recommended mounting pad size



WPMtek reserves the right to make changes to the product specification and data in this document without notice. WPMtek makes no warranty, representation or guarantee regarding the suitability of its products for any particu lar purpose, nor does WPMtek assume any liability arising from the application or use of any products or circuits, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Any enquiry ,please write to sales@wpmtek.com for futher information.